

POWER OVER ETHERNET (PoE) MAGNETICS 10/100BASE-TX VoIP Magnetics Modules

MODEL NO: HA-225 (Bottom epoxy)

FEATURE:

RoHS Compliant

RoHS peak solder rating 260°C / 3~5 Sec

Meet IEEE802.3at with 750 mA current capability.

Designed to meet IR requirement

Specifications @ 25°C

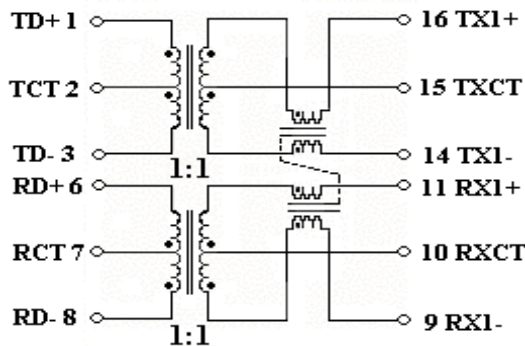
Operating temp. : -40°C ~ +85°C

Rise Time & Fall Time @ 5.0ns(Max).

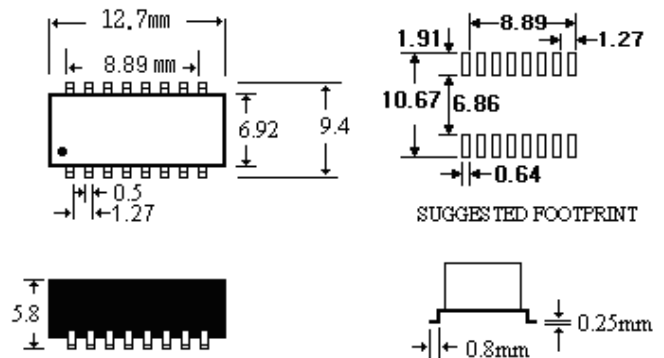
OCL : 350 uH MIN. @100KHz 100 mV 8 mA VDC

Part Number	Insertion Loss 1 to 100 MHz (dB MAX)	Cross talk (dB MIN)			Return Loss (dB MIN)				Common Mode Rejection (dB MIN)			Hi pot VAC	Cw/w (pf typ.)	DCR (MAX)
		30	60	100MHz	1-30	40	50	60-80MHz	30	60	100MHz			
HA-225	-1.2	-45	-40	-35	-16	-14	-13	-12	-43	-37	-33	1500	25	1.0

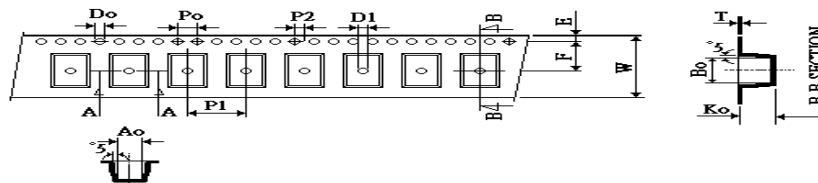
SCHEMATICS:



DIMENSION: mm
TOLERANCE: ±0.25



Packing :



DIMENSION	W	P1	PO	E	F	AO	BO	Aot
SPEC.	24.0	16.0	4.0	1.75	11.5	10.0	13.2	0.08
	+/-	0.30	0.10	0.10	0.10	0.10	0.10	(MIN)
DIMENSION	KO	P2	Do	D1	10Po	T	K1	Bot
SPEC.	6.80	2.0	1.55	1.5	40.0	0.40	6.15	0.08
	+/-	0.10	0.10	0.05	(MIN)	0.20	0.10	(MIN)

Tape & reel.....:600/reel
Tube.....:39/tub

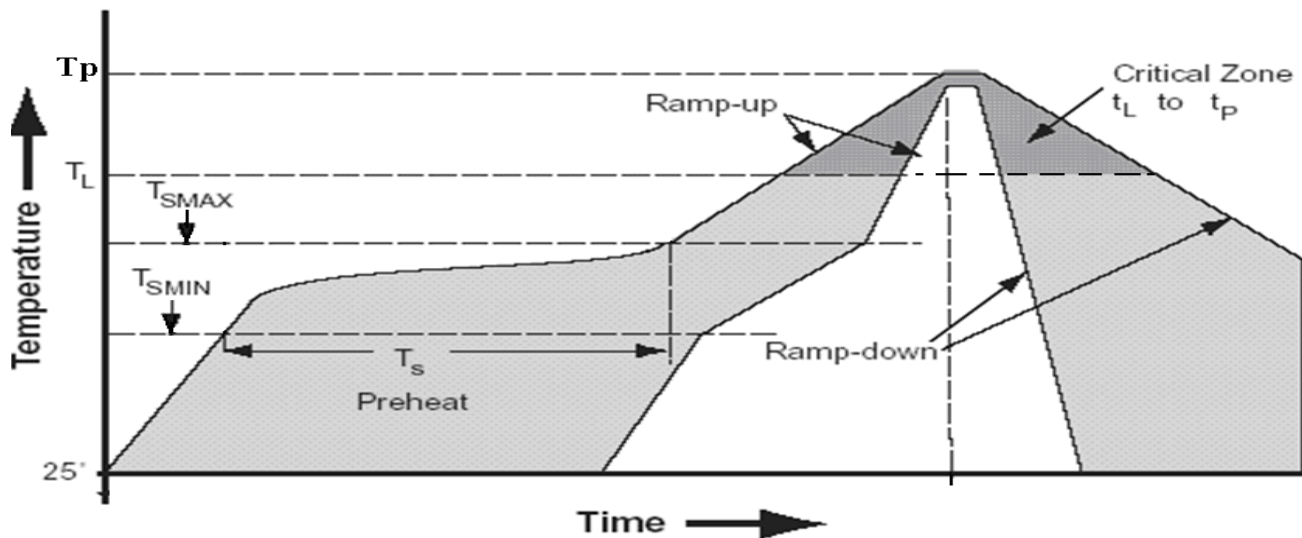
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Solder Reflow profile for Lead-Free packages.
Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.(T_s min.) Temperature Max.(T_s max.) Time (min to max) (T_s)	150 °C 200 °C 60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	217 °C 60-150 sec	
Peak Tempure (T_p) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutees Max.	

Profile



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PACKING

1. **Tape & Reel** : 600pcs / Reel , 3000pcs / Carton
2. **Dry Pack** : 1pcs
Product Description:(5g Silica Gel Desiccant)
PH: 4-8
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. **Reel Packed By Vacuum**
4. **Seal Per Jedec**

